

(1.27 mm) .050"

FLE SERIES

COST-EFFECTIVE RELIABLE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?FLE

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Au over 50 μ" (1.27 μm) Ni

Current Rating:

2.9 A per pin

(2 pins powered)

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(1.83 mm) .072" to

(4.37 mm) .172" or

pass-through

Normal Force:

100 grams (0.98 N)

Max Cycles:

100+

RoHS Compliant:

Yes

Board Mates:

FTSH, FTS, FW

Cable Mates:

FFMD*, FMTF

Tiger Beam™ contact

Ideal for pass-through applications



Surface mount

*Note: Standard FFMD callout will not mate with FLE, SFMC. Must use gold plated callouts. (See drawing on web.)

HIGH-SPEED CHANNEL PERFORMANCE

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

8 Gbps

(1.27 mm) .050" micro pitch

Available with optional pick & place pads



PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

RECOGNITIONS

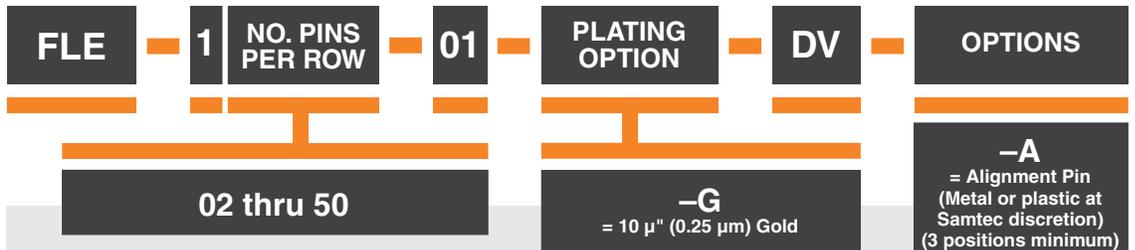
For complete scope of recognitions see www.samtec.com/quality



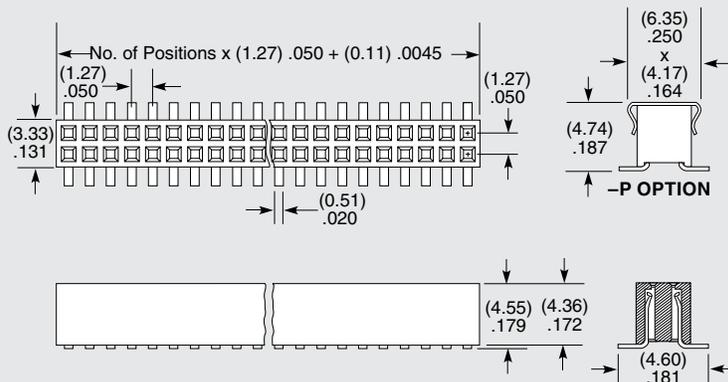
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ALSO AVAILABLE (MOQ Required)

- Other platings



- A = Alignment Pin (Metal or plastic at Samtec discretion) (3 positions minimum)
- K = (4.25 mm) .167" DIA Polyimide film Pick & Place Pad (5 positions minimum)
- P = Metal Pick & Place Pad (5 positions minimum)
- TR = Tape & Reel
- FR = Full Reel Tape & Reel Packaging (Must order maximum quantities per reel. Contact Samtec for parts per reel)



Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.